

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

METHOD FOR FORMING DAMASCENE STRUCTURE  
UTILIZING PLANARIZING MATERIAL COUPLED WITH  
DIFFUSION BARRIER MATERIAL

Confirmation Number:

First Named Applicant: William Wille

Attorney Docket Number: FIS920030024US1

Search string: ( 6316167 or 20020164877 or 20010036748 or 20020012876 ).pn.

Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

| init | Cite.No. | Patent No. | Date       | Patentee             | Kind | Class | Subclass |
|------|----------|------------|------------|----------------------|------|-------|----------|
| EC   | 1        | 6316167    | 2001-11-13 | Angelopoulos, et al. |      |       |          |

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

| init | Cite.No. | Pub. No.    | Date       | Applicant            | Kind | Class | Subclass |
|------|----------|-------------|------------|----------------------|------|-------|----------|
| EC   | 1        | 20020164877 | 2002-11-07 | Catabay, et al.      |      |       |          |
| J    | 2        | 20010036748 | 2001-11-01 | Rutter, Jr., et al.  |      |       |          |
| ✓    | 3        | 20020012876 | 2002-01-31 | Angelopoulos, et al. |      |       |          |

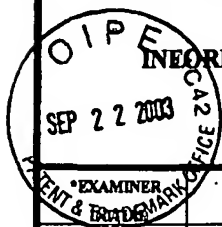
Signature

*Eric Chen*

1/13/05

Examiner Name

Date



# INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

FIS920030024US1

Application Number

10/604,056

Applicant(s)

William Wille, et al.

Filing Date

6/24/03

Group Art Unit

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

"A High Performance 0.13 um Copper BEOL Technology with Low-K Dielectric" R.D. Goldblatt, et al. Proceedings of the IEEE 2000 International Interconnect Technology Conference, 5-7 June, 2000, pp. 261-263.

"A Manufacturable Copper/Low-k SiOC/SiCN Process Technology for 90nm-node High Performance eDRAM", K. Higashi, et al, Proceedings of the IEEE 2002 International Interconnect Technology Conference, 3-5 June 2002, pp. 15-17.

"A High Resolution 248 nm Bilayer Resist" Qinghuang Lin, et al., Proc. SPIE - Int. Soc. Opt. Eng. (USA), vol. 3678, pt. 1-2 pp. 241-50.

"Surface treatment validation of inorganic BARC on 0.25 um Non Volatile Memory technology", Y. Trouilleret al. Microelectronic Engineering 46 (1999), pp. 47-50.

"Effects of Crosslinking Agent on Lithographic Performance of Negative-Tone Resists Based on Poly (p-hydroxystyrene)", Qinghuang Lin, et al. Proc. SPIE - Int. Soc. Opt. Eng. (USA), vol 3049, pp. 974-87.

Patent Application, Serial Number 09/256,034, dated 2/23/99, Inventors M. Angelopoulos, et al. Entitled Multilayered Resist System Using Tuned Polymer Films as Underlayers and Methods of Fabrication Thereof.

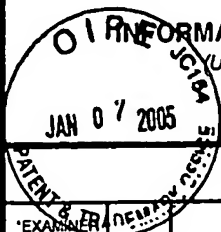
EXAMINER

*Eric Chen*

DATE CONSIDERED

1/19/05

\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



## OFFICE INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.  
FIS920030024US1SERIAL NO.  
10/604,056FILING  
6/24/03

GROUP

## U.S. PATENT DOCUMENTS

| EXAMINER<br>INITIAL | DOCUMENT NUMBER | DATE      | NAME              | CLASS | SUBCLASS | FILING DATE<br>IF APPROPRIATE |
|---------------------|-----------------|-----------|-------------------|-------|----------|-------------------------------|
| EC                  | 6,720,256       | 4/13/2004 | Wu, et al.        |       |          |                               |
| EC                  | 2004/0018721    | 1/29/2004 | Kim, et al.       |       |          |                               |
| EC                  | 6,365,529       | 4/2/2002  | Hussein, et al.   |       |          |                               |
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|                     |                 |           |                   |       |          |                               |
|                     |                 |           |                   |       |          |                               |
|                     |                 |           |                   |       |          |                               |
|                     |                 |           |                   |       |          |                               |

## FOREIGN PATENT DOCUMENTS

|    | DOCUMENT NUMBER | DATE       | COUNTRY | CLASS | SUBCLASS | TRANSLATION |    |
|----|-----------------|------------|---------|-------|----------|-------------|----|
|    |                 |            |         |       |          | YES         | NO |
| EC | JP2000208620A   | 2000-07-28 | Japan   |       |          |             |    |
|    |                 |            |         |       |          |             |    |
|    |                 |            |         |       |          |             |    |
|    |                 |            |         |       |          |             |    |
|    |                 |            |         |       |          |             |    |

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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EXAMINER

*Eric Chan*

DATE CONSIDERED

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